

ABSTRACT

In one embodiment, a semiconductor device includes a first insulator, a plurality of interconnections provided in the first insulator. The device further includes a second insulator
5 provided on the first insulator and the plurality of interconnections, and a conductor provided on a first interconnection among the plurality of interconnections and having a shape that is projected upwardly with respect to the first interconnection in the second insulator. The device further includes a plug provided on the first
10 interconnection via the conductor. The device further includes a first pad provided above the plug and electrically connected to the plug, and a second pad provided on the first pad and electrically connected to the first pad.